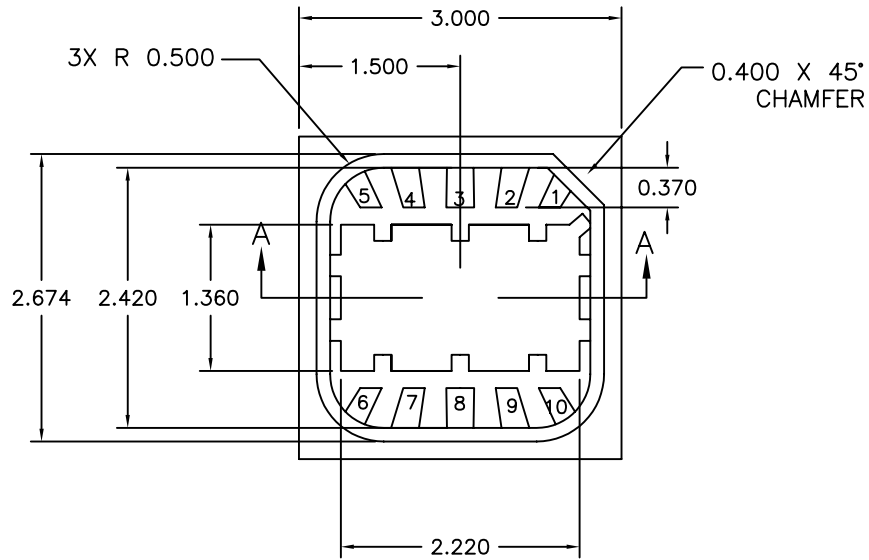
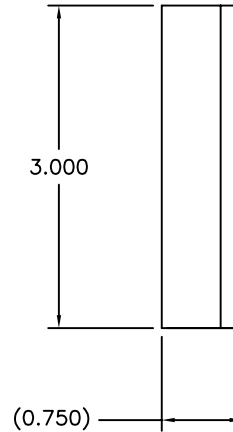


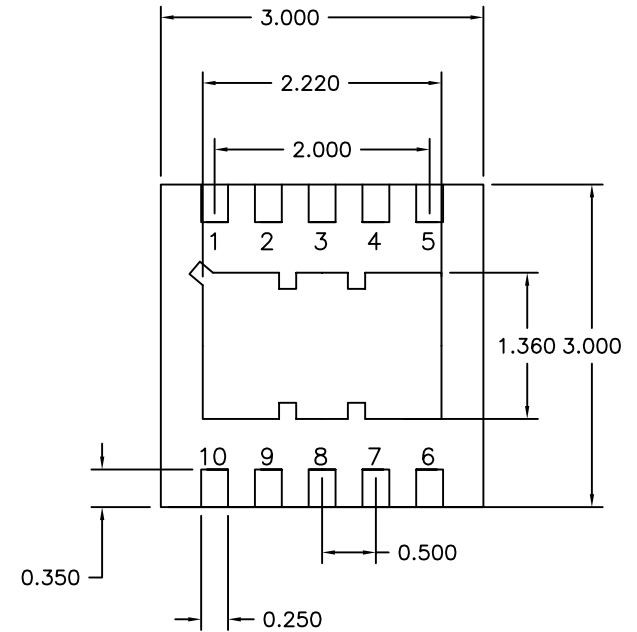
SEMPAC REVISIONS			
ECN NO.	DATE	DESCRIPTION	APPROVED
10824	12/11/06	PRODUCTION RELEASE	D.MORRIS



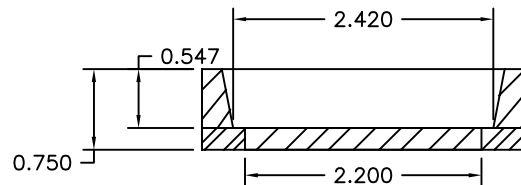
TOP VIEW



SECTION A-A



BOTTOM VIEW



NOTES:

1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
3. LEAD FRAME: COPPER, 194 FH.
4. LEAD FINISH: FULL GOLD PLATE.
5. FRAME THICKNESS: 0.2030 ± 0.0076.
6. DIE PAD: 1.360mm X 2.200mm.
7. JEDEC OUTLINE REFERENCE: MO-229 (VEED-3)

<p>THIRD ANGLE PROJECTION</p>	<p>DRAWN BY C. CRUZ</p>	<p>DATE 12/11/06</p>
	<p>APP BY P. FLASKERUD</p>	<p>DATE 12/11/06</p>
<p>CUSTOMER ---</p>		
<p>UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE:</p> <p>X.XX ± 0.015 X.XXXX ± ---</p> <p>X.XXX ± 0.050 ANGLES: ± 1°</p>		
<p>DO NOT SCALE DRAWING</p>		

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<p><b>SEMPAC, INC.</b>  <b>Open-Pak™ Technologies</b>  <b>www.sempac.com</b>          568 E. WEDDELL DRIVE, SUITE 5          SUNNYVALE, CALIFORNIA 94089          PHONE: (408) 400-9002 FAX: (408) 400-9006</p>		
<p>10 LEAD 3mm X 3mm          DFN Open-Pak™</p>		
<p>SIZE A</p>	<p>PART NO. DFN3X3-10-OP-01</p>	<p>REV 1</p>
<p>SCALE NONE</p>	<p>CAD FILE DFN3X3-10-OP-01-R1.DWG</p>	<p>SHEET 1 OF 1</p>